

IN THE SPECIFICATION

Please insert a heading at page 4, between lines 23 and 24 as follows:

SUMMARY OF THE INVENTION

Please delete the heading at page 5, line 7 as follows:

DISCLOSURE OF INVENTION

Please replace the paragraph at page 8, line 15, to page 9, line 24, with the following rewritten paragraph:

As shown in Fig. 1, a solid-state EC device 10 is provided with a lower transparent conductive coating 12 made of ITO or the like on a top face of a glass substrate 11, and a groove 12b is formed in part of the lower transparent conductive coating 12 so as to provide an insulated portion 12a. The lower transparent conductive coating 12 is comprised of two portions, that is: an insulated portion 12a insulated with the groove 12b, and a body portion 12c, in order to obtain terminals for two electrodes from these portions. The width dimension of the lower transparent conductive coating 12 including the insulated portion 12a and the body portion 12c ~~[[has]]~~ is the same as that of the glass substrate 11. On a top face of the lower transparent conductive coating 12, an EC layer ~~[[12]]~~ 13 made of  $\text{WO}_3$  or the like is layered, and on a top face of the EC layer 13, an upper transparent conductive coating 14 made of ITO or the like is layered, in this sequence. A top face of the upper transparent conductive coating 14 is covered with epoxy resin 15 as a sealant, and a top face of the epoxy resin 15 is covered with an opposed glass plate 16. The upper transparent conductive coating 14 is in direct contact with the insulated portion 12a, and the body portion 12c of the lower transparent conductive coating 12 and the upper transparent conductive coating 14 are formed so as not to short-circuit, so that a terminal of the upper transparent conductive coating 14

may be led out from the insulated portion 12a. To be more specific, the EC layer 13 is formed in the groove 12b, too, and the EC layer 13 is sandwiched between the body portion 12c of the lower transparent conductive coating 12 and the upper transparent conductive coating 14, and between the body portion 12c and the insulated portion 12a of the lower transparent conductive coating 12. In addition, the epoxy resin 15 covers a side face of the EC layer 13 and the upper transparent conductive coating 14, and outer ends of the epoxy resin 15 are in contact with the insulated portion 12a and body portion 12c of the lower transparent conductive coating 12. The EC layer 13 extends in width from the groove 12b to cover almost all of the top face, but to a position just short of an outer extremity, of the body portion 12c. The upper transparent conductive coating 14 extends in width from the inner end of the insulated portion 12a to cover almost all of the top face of the EC layer 13. The epoxy resin 15 has a width dimension shorter than that of the lower transparent conductive coating 12 including the insulated portion 12a and body portion 12c, but entirely covers the EC layer 13 and the upper transparent conductive coating 14. The opposed glass plate 16 has a width dimension greater than that of the lower transparent conductive coating 12 including the insulated portion 12 and body portion 12c (*i.e.*, of the glass substrate 11) to protrude beyond both sides of the glass substrate 11.